

L Number	Hits	Search Text	DB	Time stamp
1	665	(welding welded) near3 metallurgical\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:32
2	44	((welding welded) near3 metallurgical\$2) and semiconductor and (chip die) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:32
3	2	5627406.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 08:06
4	1	5627406.pn. and (welding welded)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 08:07
5	2	5627406.pn. and metallurgical\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 08:08
6	35	(pressure near1 (welding welded)) with metallurgical\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:38
7	128	(welding welded) with metallurgical\$2 with pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:32
9	0	((welding welded) with metallurgical\$2 with pressure) and (semiconductor chip die) and (bump ball)) not ((welding welded) near3 metallurgical\$2) and semiconductor and (chip die) and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:33
8	33	((welding welded) with metallurgical\$2 with pressure) and (semiconductor chip die) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:36
10	35	((welding welded) with metallurgical\$2 with pressure) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:37
11	2	((welding welded) with metallurgical\$2 with pressure) and (bump ball)) not ((welding welded) with metallurgical\$2 with pressure) and (semiconductor chip die) and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:37
12	0	jp407130749a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:32
13	0	jp47130749a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:34
14	0	jp40292773a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:33
15	0	jp400292773a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:33
16	0	jp470130749a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:34
17	0	jp47130749	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:34

18	0	jp407130749a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:43
19	0	jp307130749a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:36
20	0	(pressure near1 (welding welded)) and ball and metallurgical\$2	JPO	2004/03/17 10:39
21	1	(pressure near1 (welding welded)) and ball and metallurgical\$2	JPO; DERWENT	2004/03/17 10:39
22	28	(pressure near1 (welding welded))and metallurgical\$2	JPO; DERWENT	2004/03/17 10:39
23	13	(pressure near1 (welding welded))and metallurgical\$2	JPO	2004/03/17 10:39
24	0	JP407130749A	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:44

L Number	Hits	Search Text	DB	Time stamp
1	0	(metallurgical\$2 near1 (bonding bond bonded)) near3 (bump ball)	JPO	2004/03/17 14:03
2	80	(metallurgical\$2 near1 (bonding bond bonded)) near3 (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 14:03
3	67	((metallurgical\$2 near1 (bonding bond bonded)) near3 (bump ball)) and semiconductor and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 14:04
4	4	((metallurgical\$2 near1 (bonding bond bonded)) near3 (bump ball)) with semiconductor and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 14:07
5	19	((metallurgical\$2 near1 (bonding bond bonded)) near3 (bump ball)) with (semiconductor chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 14:07